## **BAT 49**

### SMALL SIGNAL SCHOTTKY DIODE

#### DESCRIPTION

General purpose metal to silicon diode featuring very low turn-on voltage and fast switching. This device has integrated protection against excessive voltage such as electrostatic discharges.

#### **ABSOLUTE RATINGS** (limiting values)

Symbol	Parameter	Value	Unit	
V <sub>RRM</sub>	Repetitive Peak Reverse Voltage	80	V	
IF	Forward Continuous Current*	T <sub>a</sub> = 70 °C	500	mA
I <sub>FRM</sub>	Repetitive Peak Forward Current*	$t_p = 1s$ $\delta \le 0.5$	3	A
I <sub>FSM</sub>	Surge non Repetitive Forward Current*	$t_p \leq 10ms$	10	A
T <sub>stg</sub> T <sub>j</sub>	Storage and Junction Temperature Range		- 65 to 150 - 65 to 125	°C ℃
TL	Maximum Lead Temperature for Soldering of from Case	230	°C	

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#### THERMAL RESISTANCE

Unit	Value	Test Conditions	Symbol
°C/W	110	Junction-ambient*	R <sub>th(j-a)</sub>
	110	Junction-ambient*	R <sub>th(j-a)</sub>

#### **ELECTRICAL CHARACTERISTICS**

#### STATIC CHARACTERISTICS

Symbol	Test Conditions			Тур.	Max.	Unit
I <sub>R</sub> * *	T <sub>j</sub> = 25°C	$V_R = 80V$		B2	200	μΑ
V <sub>F</sub> * *	T <sub>j</sub> = 25°C	I <sub>F</sub> = 10mA		WW.	0.32	V
	T <sub>j</sub> = 25°C	I <sub>F</sub> = 100mA	16.1-		0.42	
	T <sub>j</sub> = 25°C	$I_F = 1A$	/		1	

#### DYNAMIC CHARACTERISTICS

	$1_{j} = 23.0$						I	
DYNAMIC C		S						
Symbol	Test Conditions		Min.	Тур.	Max.	Unit		
С	T <sub>j</sub> = 25°C f	= 1MHz	١	/ <sub>R</sub> = 0V		120		pF
			1	/ <sub>R</sub> = 5V		35		

\* On infinite heatsink with 4mm lead length \*\* Pulse test:  $t_p \leq 300 \mu s ~~\delta < 2\%$ 

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Figure 1. Forward current versus forward voltage at low level (typical values).

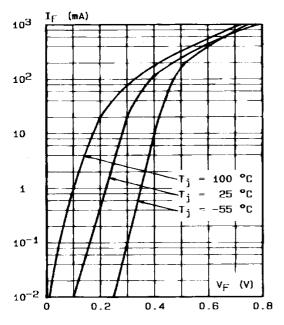


Figure 2. Forward current versus forward voltage at high level (typical values).

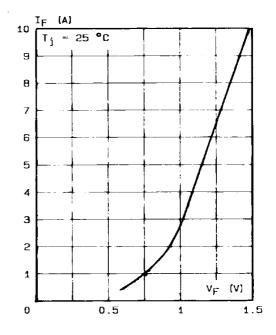


Figure 3. Reverse current versus junction temperature.

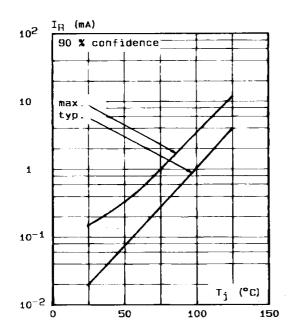
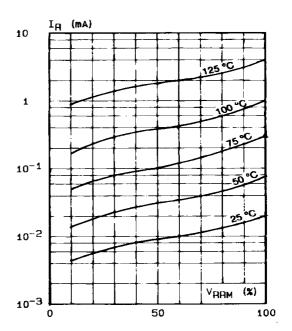


Figure 4. Reverse current versus  $V_{\mbox{\scriptsize RRM}}$  in per cent.



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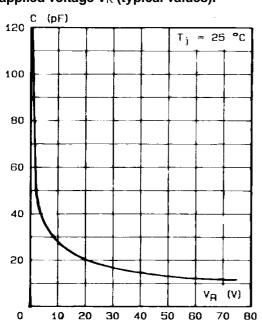


Figure 5. Capacitance C versus reverse applied voltage  $V_{\text{R}}$  (typical values).

Figure 6. Surge non repetitive forward current for a rectangular pulse with t  $\leq$  10 ms.

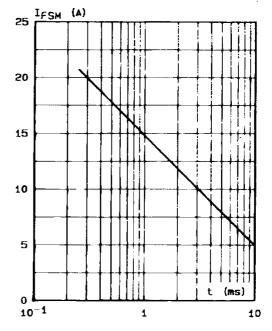
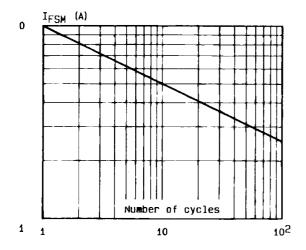
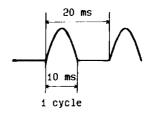


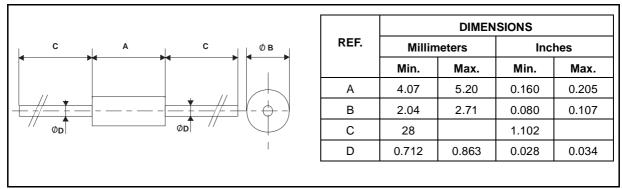
Figure 7. Surge non repetitive forward current versus number of cycles.





#### PACKAGE MECHANICAL DATA

#### DO 41 Glass



Cooling method : by convection and conduction Marking: clear, ring at cathode end. Weight: 0.34g

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